

RTC5633 : 5 GHz Frond End Module for 802.11a/n/ac

Description

The RTC5633 is a RF front-end module (FEM) with transmit/receive chain for 802.11a/n/ac WLAN applications. The device consists of a power amplifier (PA) with power detector, a low-pass filter (LPF) for harmonic rejection, a T/R switch and an RX low-noise amplifier (LNA) with bypass mode. A digital enable/disable function is also included in both PA and LNA, which allows power savings during off mode. The antenna ports are switched between transmit and receive. In the transmitting path, the FEM has a typical gain of 29 dB and delivers 16 dBm linear output power under 1.8% EVM 802.11ac 256QAM modulation. In the receiving path, the FEM can provide a typical gain of 10 dB and 2.5 dB noise figure. The RTC5633 is packaged in 16-lead surface mount package QFN 3mmx3mmx0.75mm with lead-free RoHS compliant.

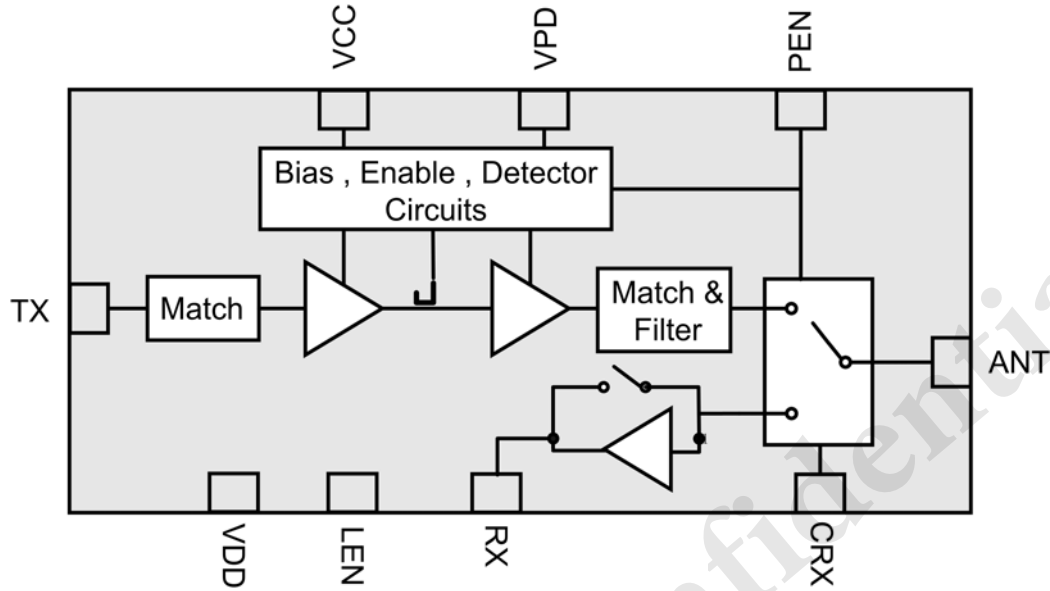
Feature

- ◆ Frequency Range: 5.15 – 5.85 GHz
- ◆ Integrated high performance PA, LNA with bypass function, harmonic filter and SPDT switch
- ◆ Input & output fully 50 ohm matching
- ◆ Output Power 16 dBm@1.8% EVM, 802.11ac, HT80, MCS9
- ◆ Output Power 18 dBm@3% EVM, 802.11a, 64QAM
- ◆ Digital Enable/Disable control
- ◆ 10 dB gain and 2.5 dB NF for RX path
- ◆ Compact & low profile package in 16L QFN-3mmx3mmx0.75mm
- ◆ RoHS, Pb-free, Halogen Free Compliant
- ◆ Moisture Sensitivity Level : MSL 3

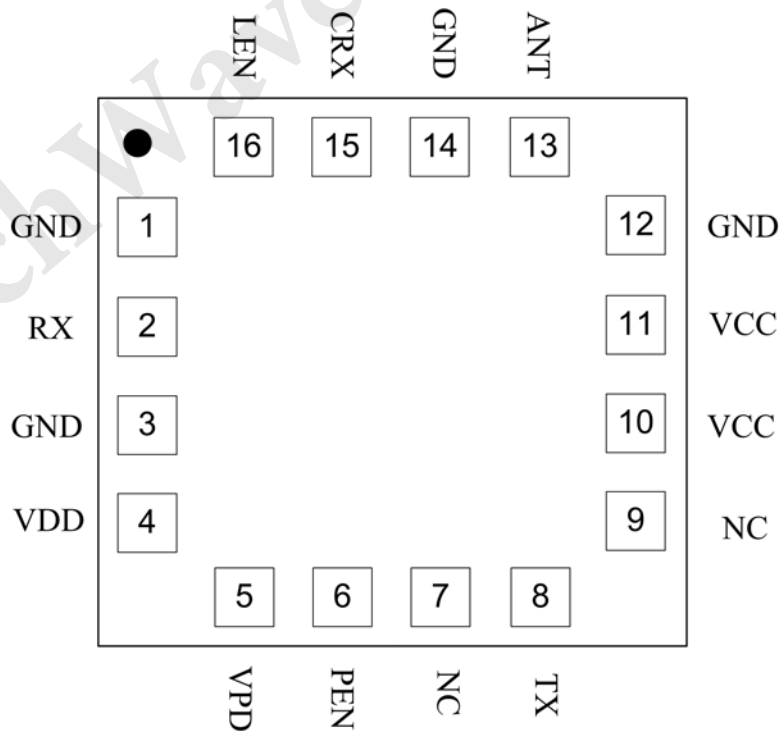
Application

- ◆ IEEE 802.11a/n/ac Wireless LAN System
- ◆ 5GHz ISM Band Application
- ◆ Cardbus, miniPCI, PCIe, AP Application

Functional Block Diagram



Pin Out (Top View through package)



Pin Function Description

| Pin | Function | Description |
|--------|----------|---|
| 1 | GND | Ground |
| 2 | RX | RF output port for LNA |
| 3 | GND | Ground |
| 4 | VDD | Supply Voltage for LNA |
| 5 | VPD | PA detector output |
| 6 | PEN | Control voltage for PA and TX switch |
| 7 | NC | Not connected |
| 8 | TX | RF input port for PA |
| 9 | NC | Not connected |
| 10 | VCC | PA Supply voltage |
| 11 | VCC | PA Supply voltage |
| 12 | GND | Ground |
| 13 | ANT | Antenna output |
| 14 | GND | Ground |
| 15 | CRX | Control voltage for RX switch |
| 16 | LEN | Control voltage for LNA |
| Paddle | | Must be connected to GND for best performance |

Truth Table

| PEN | LEN | CRX | Mode |
|------|------|------|--------------|
| High | Low | Low | TX |
| Low | High | High | RX High Gain |
| Low | Low | High | RX Bypass |

Absolute Maximum Rating

| Parameter | Rating | Units |
|---------------------------|-------------|-------|
| Supply voltage (VCC, VDD) | 4 | V |
| PA Enable Voltage (PEN) | 3.6 | V |
| LNA Enable Voltage (LEN) | 3.6 | V |
| TX Input Power | +5 | dBm |
| Operating Temperature | -30 to +85 | °C |
| Storage Temperature | -40 to +150 | °C |

Note : Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only, functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation between operation range maximum and absolute maximum for extended periods may affect device reliability.

Recommended Operating Range

| Parameter | Symbol | Min | Typ | Max | Unit |
|-------------------------------|----------------|-----|-----|-----|------|
| Supply voltage | VCC, VDD | 3.0 | 3.3 | 3.6 | V |
| PA enable voltage (High) | PEN | 2.8 | 3 | 3.3 | V |
| PA enable voltage (Low) | PEN | 0 | 0 | 0.3 | V |
| LNA Enable Voltage (High) | LEN | 2 | 3 | 3.3 | V |
| LNA Enable Voltage (Low) | LEN | 0 | 0 | 0.3 | V |
| Switch control voltage (High) | CRX | 2.8 | 3 | 3.3 | V |
| Switch control voltage (Low) | CRX | 0 | 0 | 0.3 | V |
| Operating Temperature | T _A | -30 | +25 | +85 | °C |

Electrical Specification

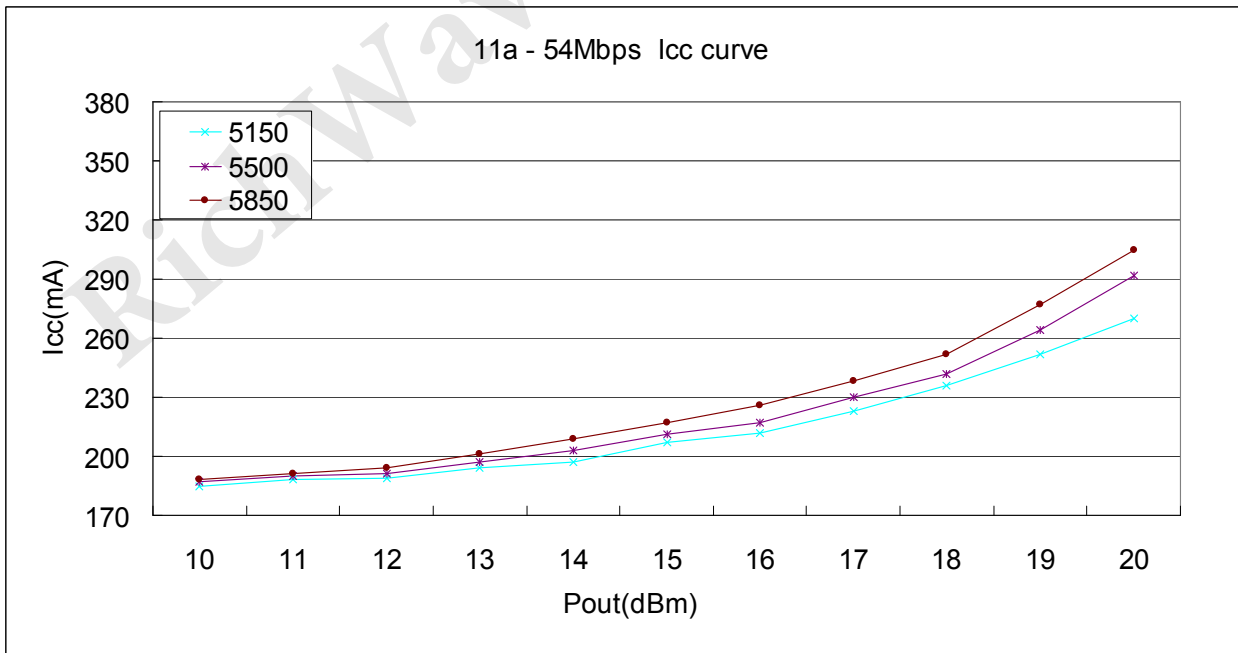
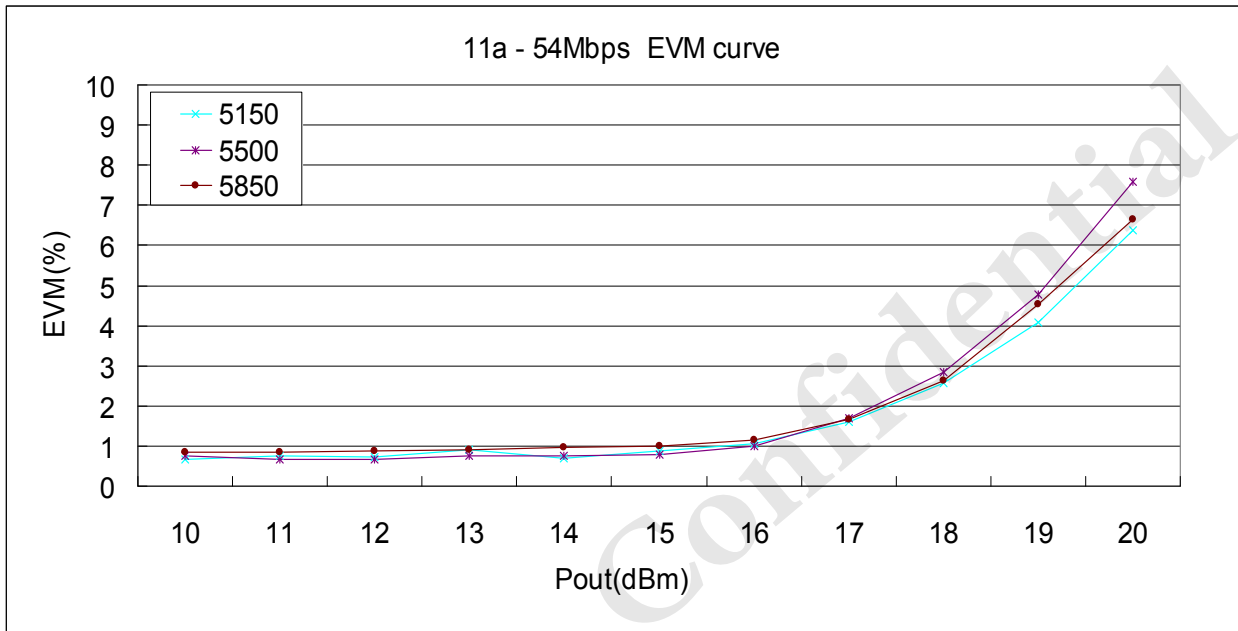
| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|--|----------|--|------|------|------|---------|
| Transmit Mode (TX – ANT) | | | | | | |
| T _A = +25 °C, VCC = VDD = 3.3 V, PEN = 3 V, all unused RF ports terminated in a 50 Ω load, unless otherwise noted | | | | | | |
| Operating Frequency | f | | 5.15 | | 5.85 | GHz |
| Output Power, High Linearity Mode, H/L=3.3V | Pout | 802.11a, 64QAM/54Mbps, EVM = 3% | | 18 | | dBm |
| | | 802.11a mask compliant power, OFDM 6Mbps | | 19 | | dBm |
| | | 802.11ac, MCS9, EVM = 1.8%, HT80 | 15 | 16 | | dBm |
| Small Signal Gain | G | Pin = -30dBm | 25 | 29 | | dB |
| Gain Flatness | | Gain Variation from 5150 to 5850MHz | -1 | | 1 | dB |
| 1 dB Output Compression Point | P1dB | 1dB power Compression | | 25 | | dBm |
| Return Loss | S11 | Input Return Loss | 5 | 6 | | dB |
| | S22 | Output Return Loss | 5 | 7 | | dB |
| 2f & 3f harmonics | 2fo, 3fo | Pout = 18 dBm, 6Mbps, 802.11a | | -36 | | dBm/MHz |
| All Spurious | | Pout = 18 dBm, 6Mbps, 802.11a | | -36 | | dBm/MHz |
| Isolation | ISO | From Ant to either TX or RX pin | 35 | 47 | | dB |
| Power Detector Output | Vpd | Pout = 10dBm | | 0.4 | | V |
| | | Pout = 20dBm | | 1.25 | | V |
| Supply Current | Icq | Quiescent (no RF) | | 175 | 210 | mA |
| PA Enable Current | Ien | Quiescent (no RF) | | 1 | | μA |
| Supply Current, Transmit Mode | Icc | Pout = 18 dBm, 802.11a, 64QAM | | 240 | | mA |

| | | | | | | |
|---|-----------------|------------------------------------|------|-----|------|-----|
| | | Pout = 16 dBm, 802.11ac, 256QAM | | 230 | | mA |
| Receive High Gain Mode T _A = +25 °C, VDD = 3.3 V, LEN = CRX = 3 V, all unused RF ports terminated in a 50 Ω load, unless otherwise noted | | | | | | |
| Operating Frequency | f | | 5.15 | | 5.85 | GHz |
| RX Gain | G | High Gain Mode | 8 | 10 | | dB |
| Return Loss | S11 | Input Return Loss | 3 | 4 | | dB |
| | S22 | Output Return Loss | 5 | 7 | | dB |
| Noise Figure | NF | High Gain Mode | | 2.5 | | dB |
| 1 dB Input Compression Point | IP1dB | 1dB Gain Compression | | -8 | | dBm |
| Supply Current | I _{dd} | RX ON | | 11 | 14 | mA |
| Receive Bypass Mode T _A = +25 °C, VDD = 3.3 V, LEN = 0 V, CRX = 3 V, all unused RF ports terminated in a 50 Ω load, unless otherwise noted | | | | | | |
| Operating Frequency | f | | 5.15 | | 5.85 | GHz |
| RX Gain | G | Bypass Mode | | -10 | | dB |
| Return Loss | S11 | Input Return Loss | | 3 | | dB |
| | S22 | Output Return Loss | | 5 | | dB |
| Supply Current | I _{dd} | RX ON | | 0.2 | | μA |

Typical Transmit Characteristics

EVM and Icc at 802.11a 64QAM 54Mbps

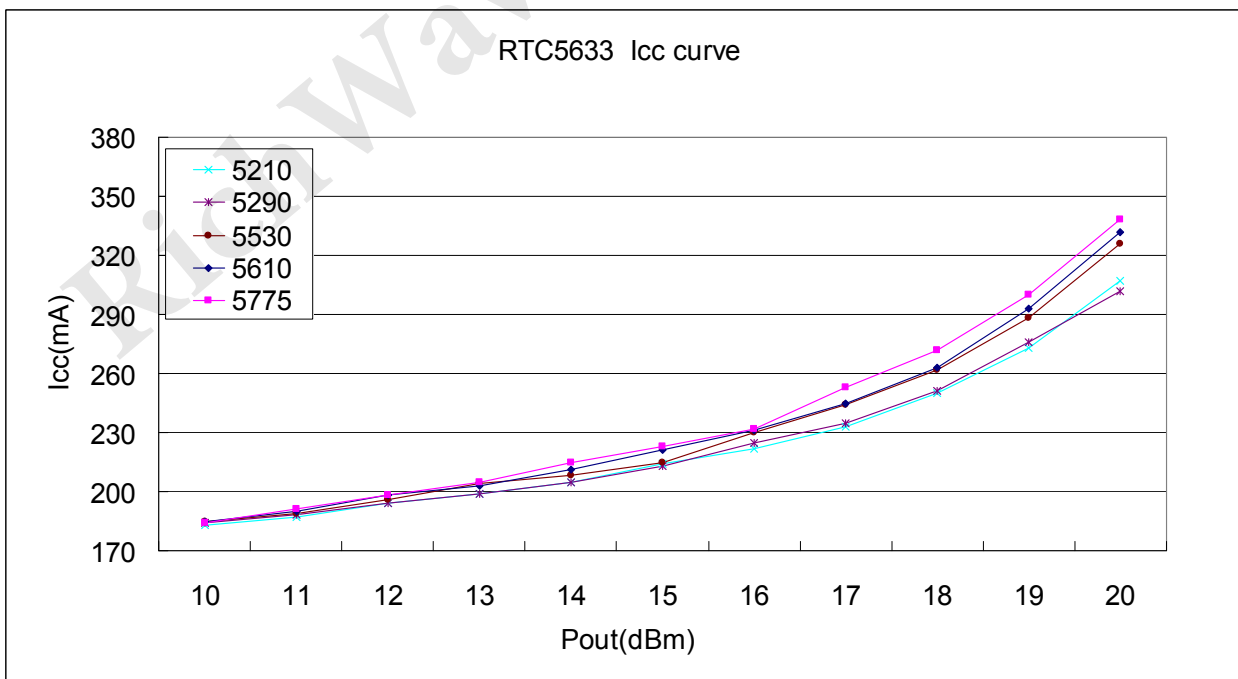
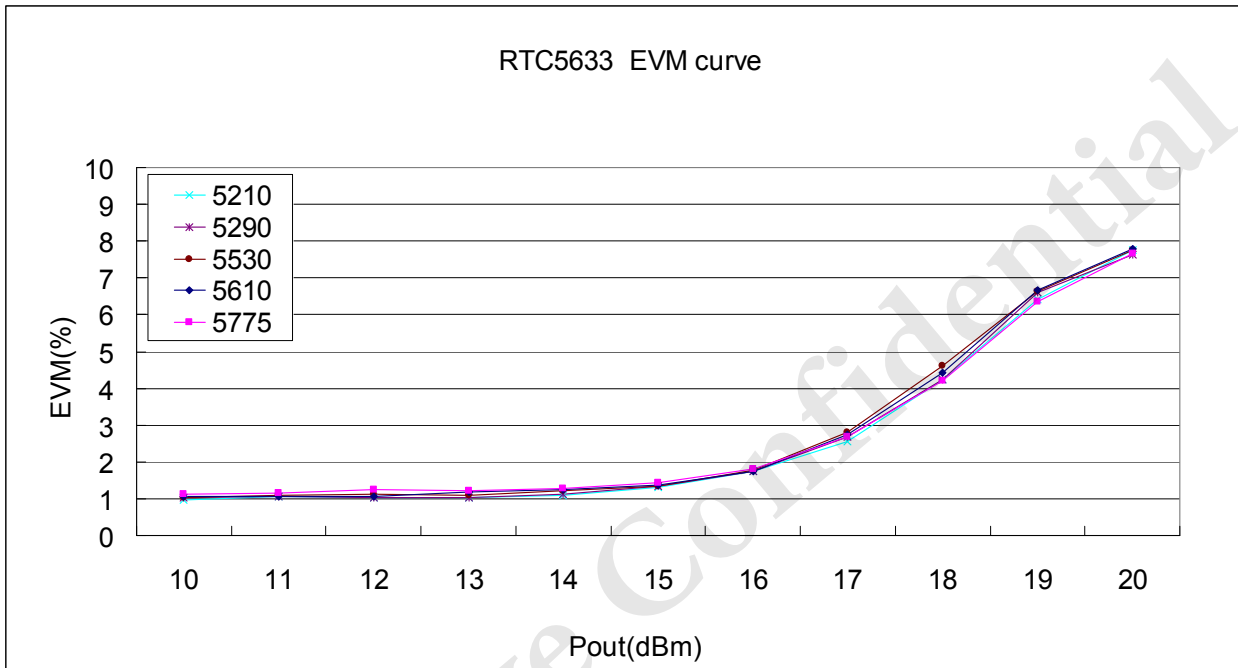
T = 25°C, VCC = VDD = 3.3 V, PEN = 3 V



Typical Transmit Characteristics

EVM and Icc at 802.11ac 256QAM HT80

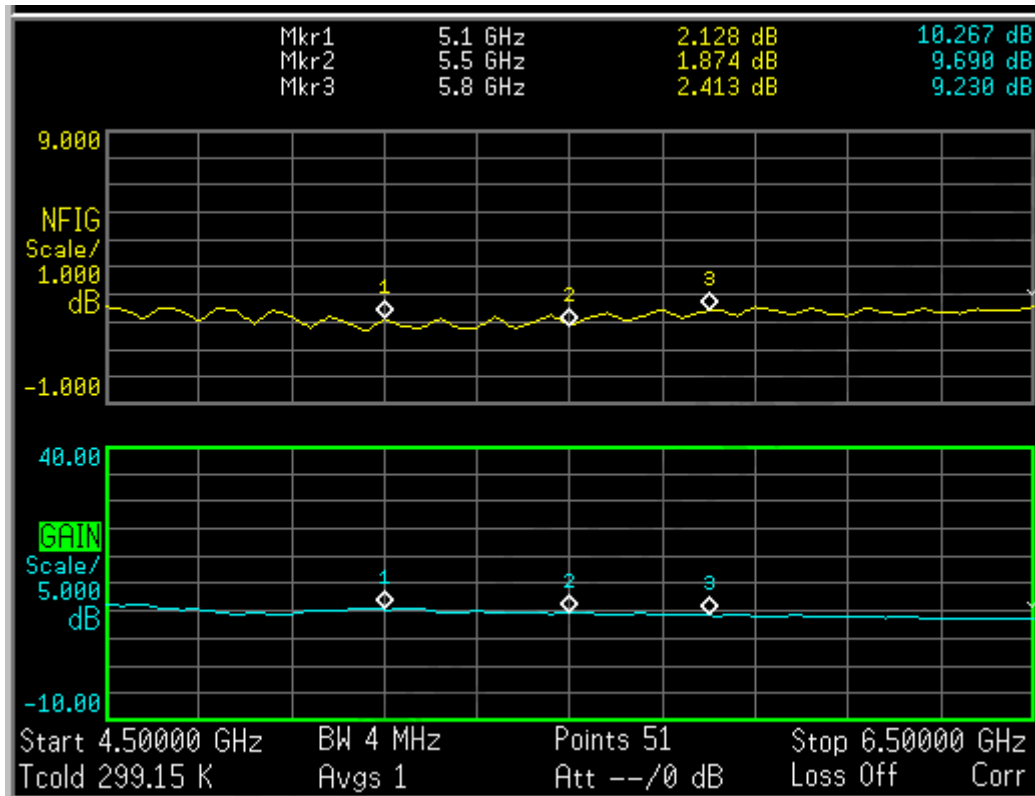
T = 25°C, VCC = VDD = 3.3 V, PEN = 3 V



Typical Receive Characteristics (High Gain Mode)

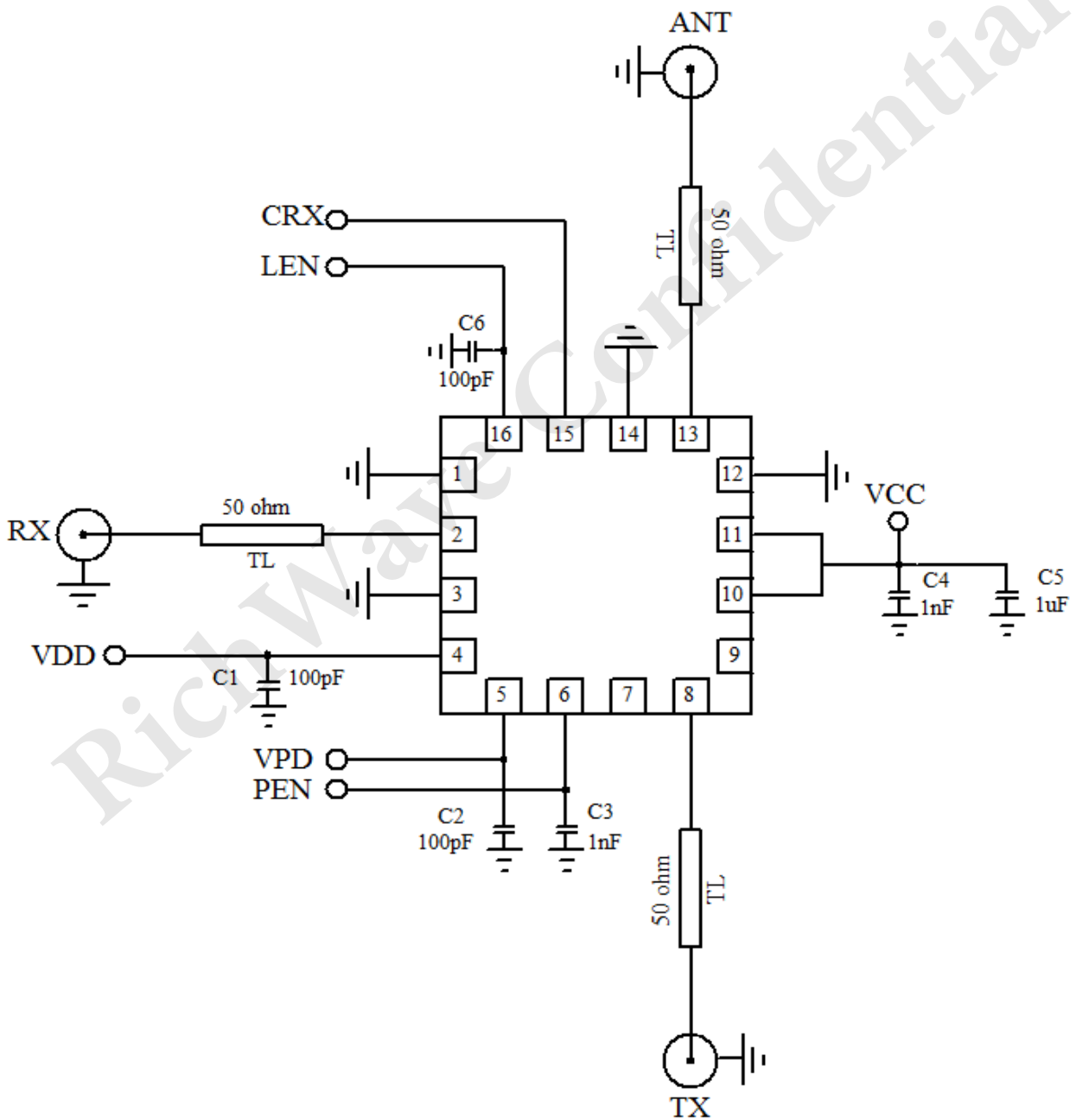
Noise Figure

T = 25°C, VCC = VDD = 3.3 V, LEN = CRX = 3 V

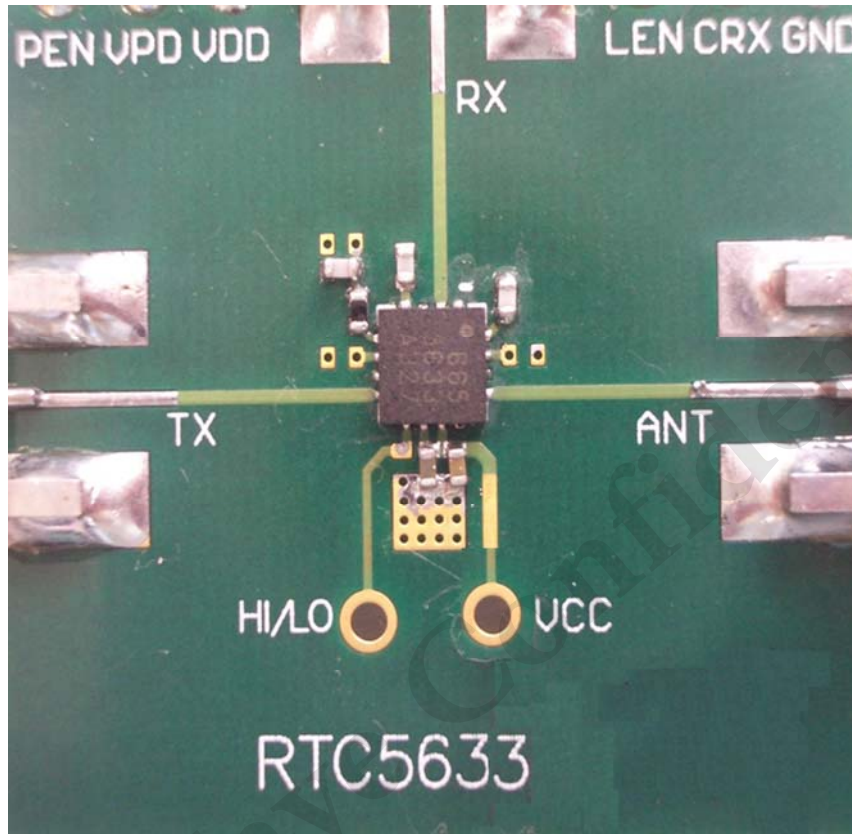


Application Circuit

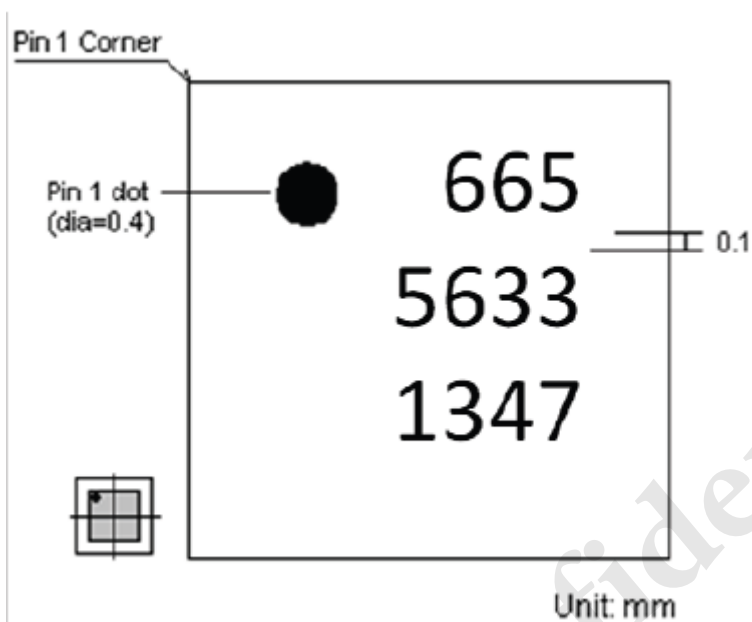
The application circuit and below evaluation board are used for the performance test of RTC5633 (5GHz 11ac FEM). The RF characteristics of RTC5633 shown in the specification table are measured by the evaluation board. Evaluation board setup procedure: (1) connect GND to PCB backside (2) Apply 3.3V to Vcc pad (3) Select test path according to control truth table.



Evaluation Board Photograph



Marking Specifications



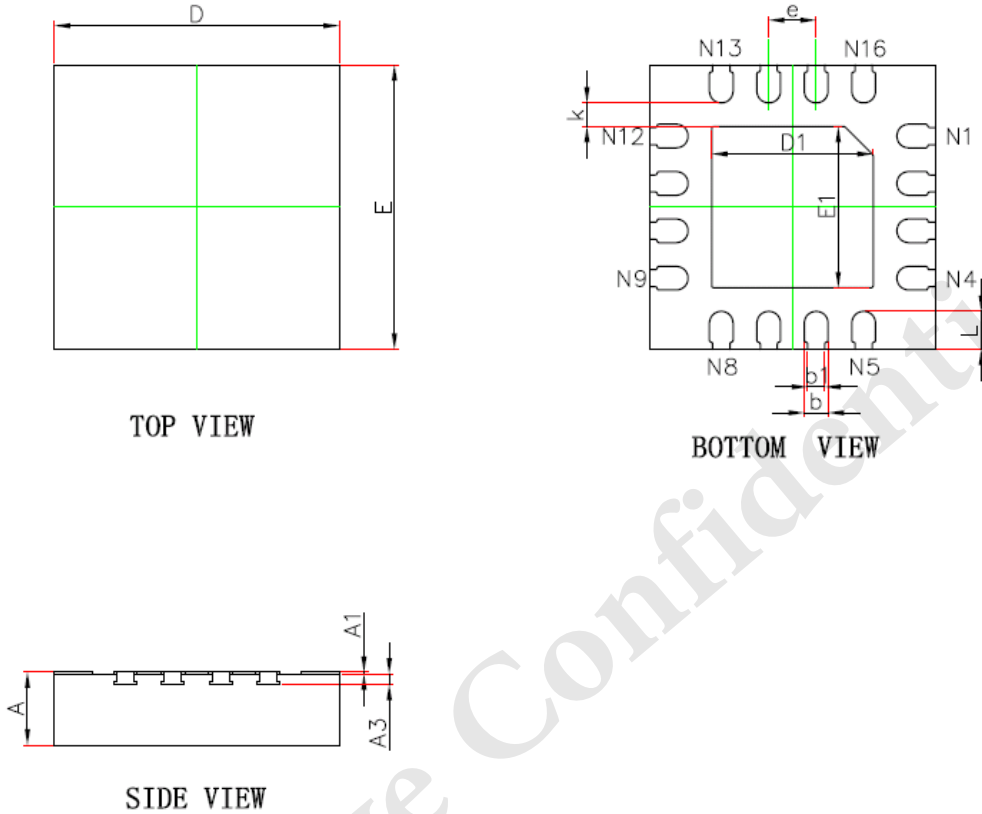
| | Description | Position | Font Type | Height | Width | Space |
|-------|-------------|----------|-----------|--------|--------|--------|
| Line1 | 665 | Right | HELV.FNT | 0.60mm | 0.40mm | 0.10mm |
| Line2 | 5633 | Right | HELV.FNT | 0.60mm | 0.40mm | 0.10mm |
| Line3 | 1347 | Right | HELV.FNT | 0.60mm | 0.40mm | 0.10mm |

Lin1=665~Wafer Lot Number

Lin2=5633~Device name

Lin3=1~Wafer ID 3~Year Code: 2013; 47~week Code

Package Outline Dimension

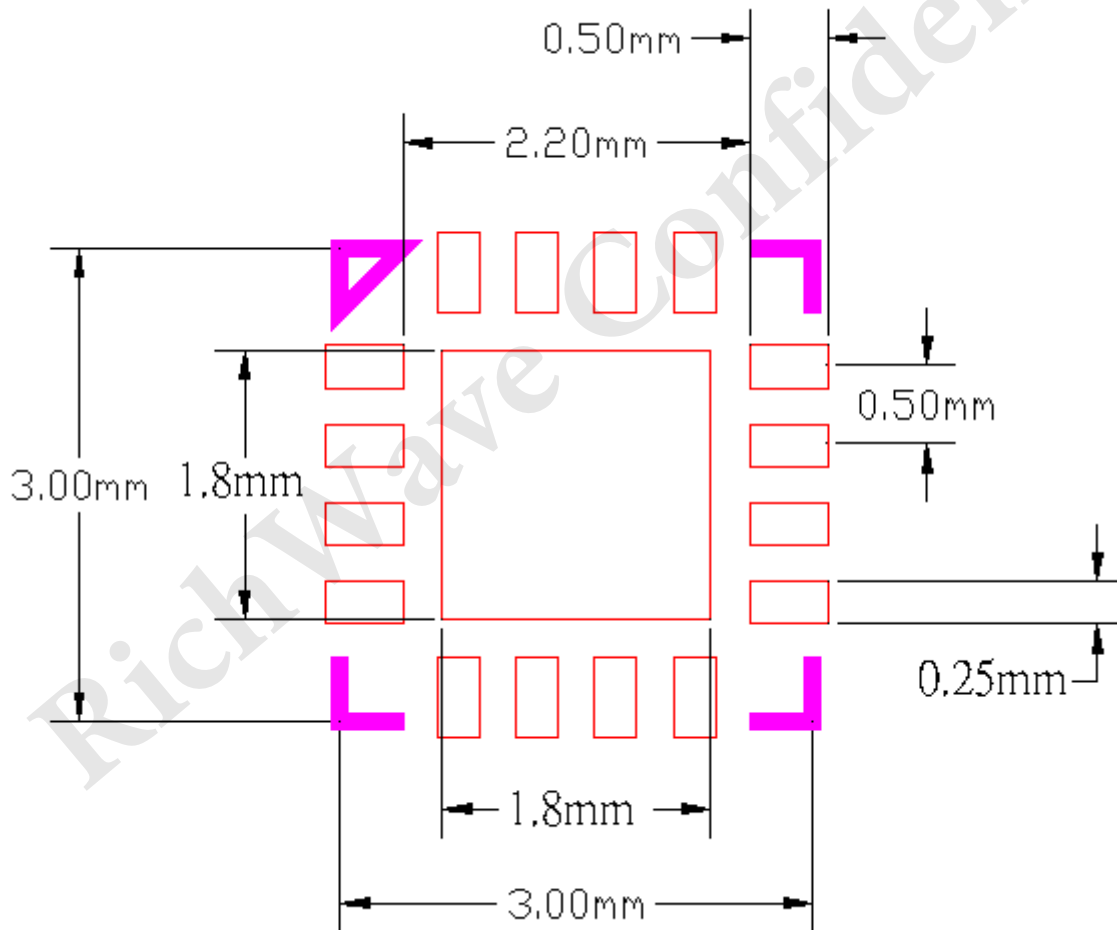


| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 0.700 | 0.800 | 0.028 | 0.031 |
| A1 | -0.004 | 0.046 | 0.000 | 0.002 |
| A3 | 0.110REF. | | 0.004REF. | |
| D | 2.924 | 3.076 | 0.115 | 0.121 |
| E | 2.924 | 3.076 | 0.115 | 0.121 |
| D1 | 1.600 | 1.800 | 0.063 | 0.071 |
| E1 | 1.600 | 1.800 | 0.063 | 0.071 |
| k | 0.200MIN. | | 0.008MIN. | |
| b | 0.200 | 0.300 | 0.008 | 0.012 |
| b1 | 0.130 | 0.230 | 0.005 | 0.009 |
| e | 0.500TYP. | | 0.020TYP. | |
| L | 0.350 | 0.450 | 0.014 | 0.018 |

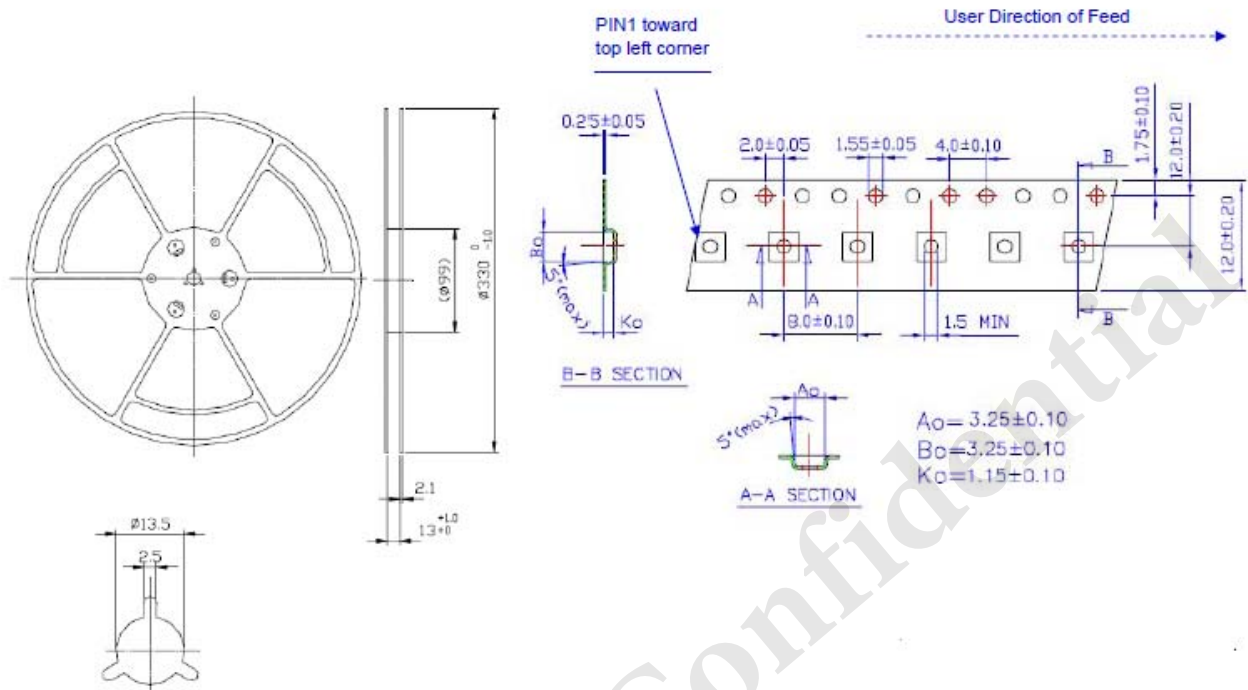
Package and Handling

The device is moisture sensitive and should be handled within proper MSL 3 guidelines to avoid damage from moisture absorption and exposure. Any unused devices after the MBB (Moisture Barrier Bag) has been opened for more than 48 hours or not stored at <10% RH should be baked before any subsequent reflow and board assembly. Re-baking should be done for a minimum of 8 hours at 125°C. Unused devices can either be baked and dry-packed first before storage, or they can be baked just before the next board assembly.

Recommended PCB Land Pattern



Tape and Real Dimension



Unit : mm

Recommended Solder Reflow Profiles

| | |
|--|-----------------|
| Average ramp-up rate (200°C to peak) | 3°C/second max. |
| Preheat temperature 175 (+/-25) °C | 60~120secs |
| Temperature maintained above 217°C | 60~150secs |
| Time within 5°C of actual peak temperature | 30 seconds min. |
| Peak temperature range | (260 +2/-2)°C |
| Ramp down rate | 6°C/second max. |
| Time 25°C to peak temperature | 8 minutes max. |

* Follow JEDEC spec J-STD-020D

